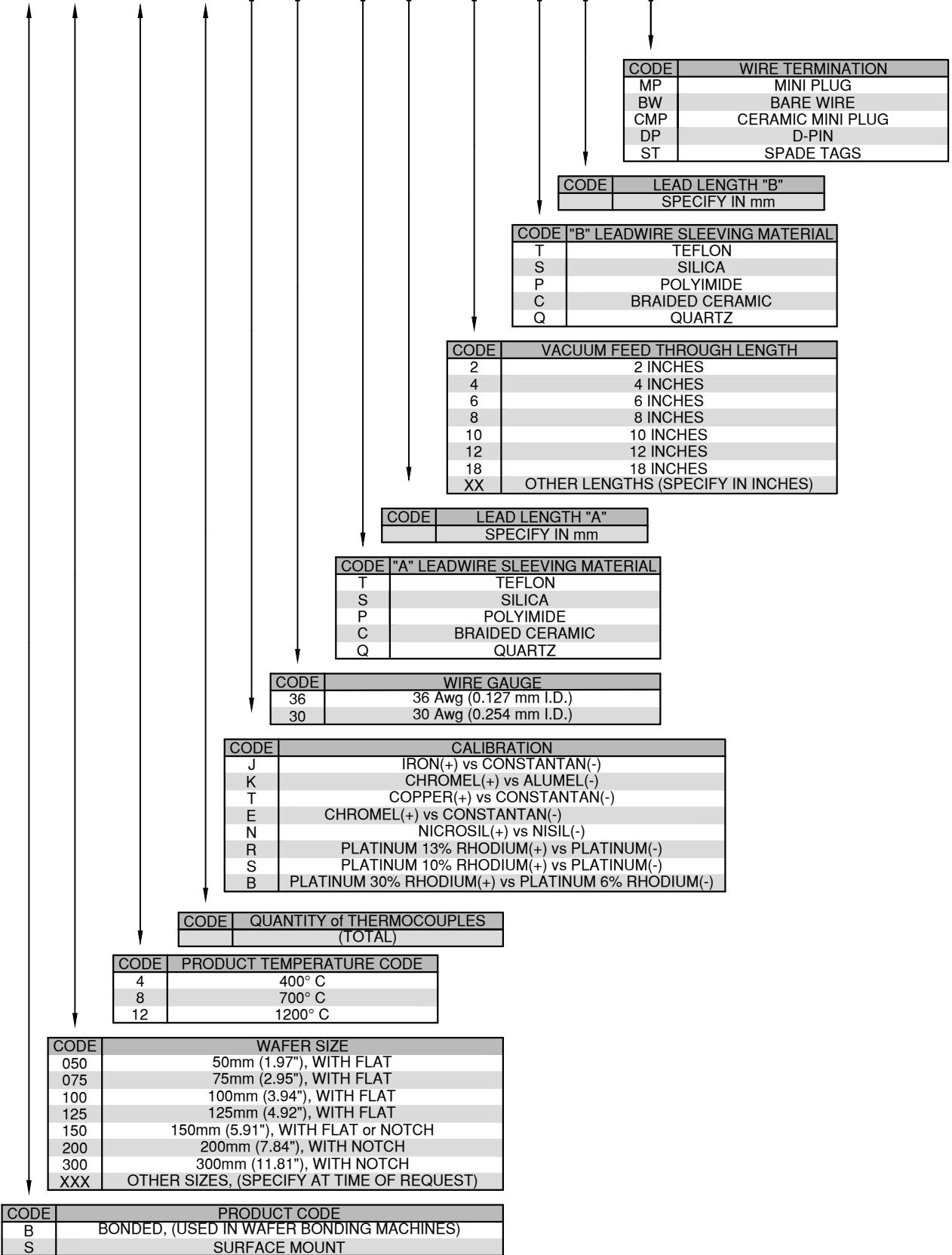


# WAFER TEMPERATURE SENSORS

## CONFIGURATION CODE

S 100 - 8 - 1 K 36 - S 100 - 4 - T 300 - MP



CODE	WIRE TERMINATION
MP	MINI PLUG
BW	BARE WIRE
CMP	CERAMIC MINI PLUG
DP	D-PIN
ST	SPADE TAGS

CODE	LEAD LENGTH "B"
	SPECIFY IN mm

CODE	"B" LEADWIRE SLEEVING MATERIAL
T	TEFLON
S	SILICA
P	POLYIMIDE
C	BRAIDED CERAMIC
Q	QUARTZ

CODE	VACUUM FEED THROUGH LENGTH
2	2 INCHES
4	4 INCHES
6	6 INCHES
8	8 INCHES
10	10 INCHES
12	12 INCHES
18	18 INCHES
XX	OTHER LENGTHS (SPECIFY IN INCHES)

CODE	LEAD LENGTH "A"
	SPECIFY IN mm

CODE	"A" LEADWIRE SLEEVING MATERIAL
T	TEFLON
S	SILICA
P	POLYIMIDE
C	BRAIDED CERAMIC
Q	QUARTZ

CODE	WIRE GAUGE
36	36 Awg (0.127 mm I.D.)
30	30 Awg (0.254 mm I.D.)

CODE	CALIBRATION
J	IRON(+) vs CONSTANTAN(-)
K	CHROMEL(+) vs ALUMEL(-)
T	COPPER(+) vs CONSTANTAN(-)
E	CHROMEL(+) vs CONSTANTAN(-)
N	NICROSIL(+) vs NISIL(-)
R	PLATINUM 13% RHODIUM(+) vs PLATINUM(-)
S	PLATINUM 10% RHODIUM(+) vs PLATINUM(-)
B	PLATINUM 30% RHODIUM(+) vs PLATINUM 6% RHODIUM(-)

CODE	QUANTITY of THERMOCOUPLES (TOTAL)

CODE	PRODUCT TEMPERATURE CODE
4	400° C
8	700° C
12	1200° C

CODE	WAFER SIZE
050	50mm (1.97"), WITH FLAT
075	75mm (2.95"), WITH FLAT
100	100mm (3.94"), WITH FLAT
125	125mm (4.92"), WITH FLAT
150	150mm (5.91"), WITH FLAT or NOTCH
200	200mm (7.84"), WITH NOTCH
300	300mm (11.81"), WITH NOTCH
XXX	OTHER SIZES, (SPECIFY AT TIME OF REQUEST)

CODE	PRODUCT CODE
B	BONDED, (USED IN WAFER BONDING MACHINES)
S	SURFACE MOUNT

